



Description

- TOTAL POLYSTYRENE FT875 is high heat resistance, high impact stress, V1 non-halogenated flame retardant with high level of stress crack resistance.
- This grade has excellent mechanical properties and good abrasion and tear resistance.

Applications

- Electronics packaging
- Base Resin for Conductive Compound

Properties	Method	Unit	Value (*)
Rheological			
Melt Flow Index (200°C/5kg)	ISO 1133	g/10min	3.0
Thermal			
Vicat Softening Point 10N (T° increase = 50°C/h)	ISO 306	°C	101
Coefficient of Linear Thermal Expansion	-	mm/°C	8.90
Mechanical			
Notched Izod Impact Strength	ISO 180	kJ/m ²	10
Tensile Strength at Yield	ISO 527	MPa	30
Elongation at Break	ISO 527	%	35
Flexural Modulus	ISO 178	MPa	1900
Rockwell Hardness	ISO 2039	-	R93
Electrical			
Dielectric Strength	-	kV/mm	160
Surface Resistivity	ISO IEC 93	Ohms	>10 ¹³
Others			
Density	ISO 1183	g/cm ³	1.14
Moulding Shrinkage	-	%	0.4-0.7
Water Absorption	ISO 62	%	<0.1
UL 94 Class	UL 94	-	V1 @ 2.5 mm

(*) Data not intended for specification purposes.

*All tests have been carried out at 23°C unless otherwise stated.

*Mechanical properties have been measured on injection molded test specimens.

*Bulk density is approximately 0.6 g/cm³.

General Information

- Processing condition: Temperatures during extrusion/injection should be below 240°C.
- Recommended Pre-dry condition: 70°C for 2 hours.